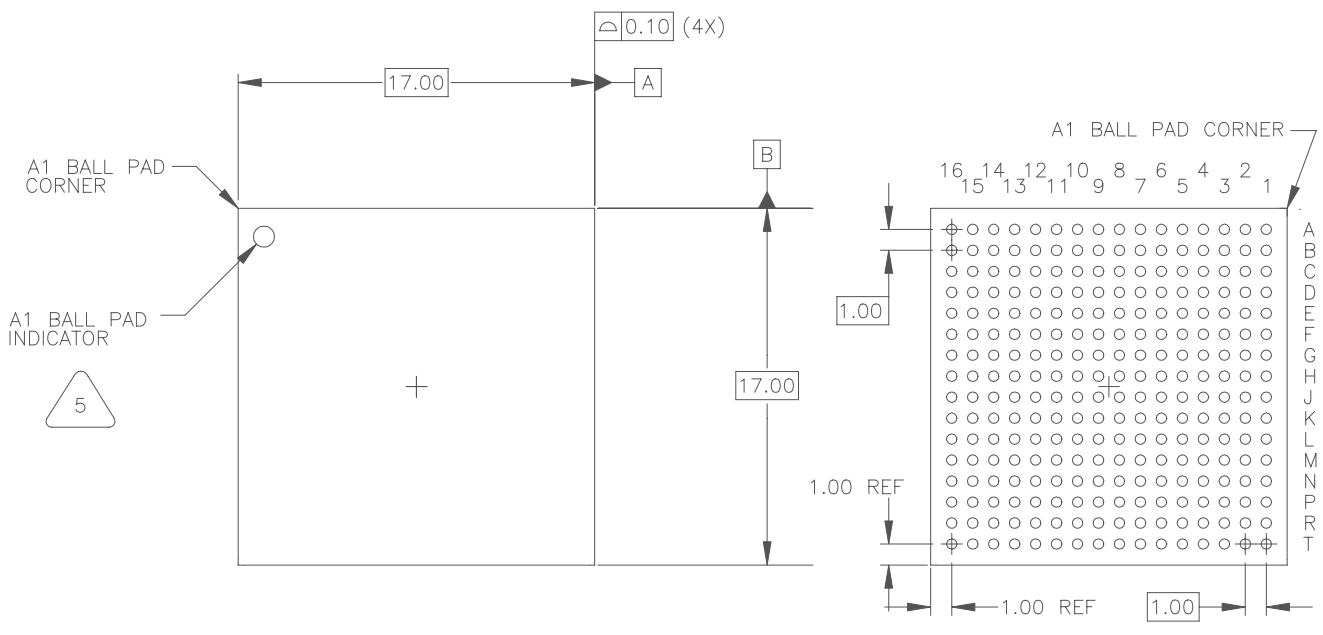
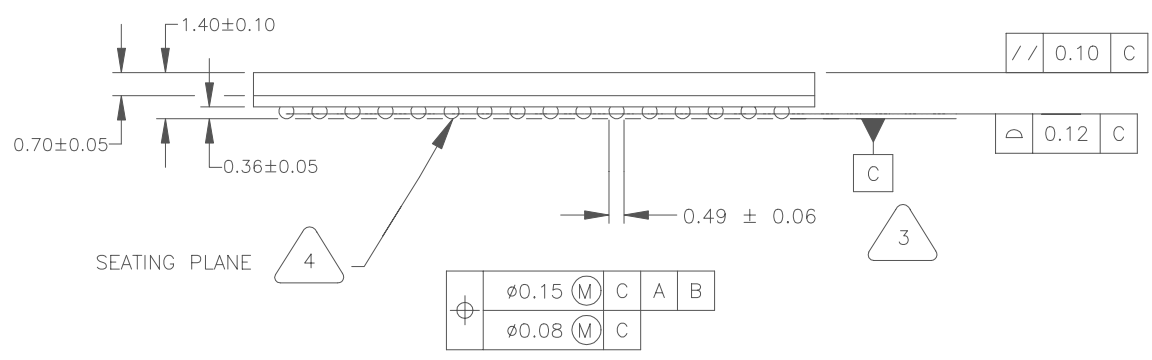


REVISIONS			
LTR.	DESCRIPTION	DATE	APPROVED
A	NEW DRAWING	01/03	



TOP VIEW

BOTTOM VIEW
(BALL SIDE)



SIDE VIEW

NOTES:

1. DIMENSION IS MM.
 2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
- ③. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- ④. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- ⑤. A1 BALL PAD CORNER I.D.

SIGNATURE		DATE									
DOC. CONTROL:								TITLE			
ENGR. MGR:								MARKETING OUTLINE DRAWING			
MFG. ENGR:								17MM X 17MM, 256 BALLS, CSBGA, 2 LAYER 1.00 MM PITCH			
CHECKED BY:	TWM	12/02	SIZE	FSCM NO.	PART NO.	56-G6021-001	REV.				
DRAWN BY:	JFD	12/02	A				A				
SCALE				N/A		SHEET 1 of 1					